



**Glass cloth base epoxy resin
flame retardant copper clad laminate**

UV BLOCK FR-4-86

■ FEATURES

- High luminance of epoxy contrast with copper for laser type A.O.I.
- UV solder mask may be applied simultaneously to increase yields.
- High performance epoxy blended to achieve higher heat resistance than that of FR-4-86
- Thickness 0.8mm capability.

■ PERFORMANCE LIST

Characteristics	Unit	Conditioning	Typical Values	SPEC	Test Method
Volume resistivity	MΩ·cm	C-96/35/90	$5 \times 10^8 \sim 5 \times 10^9$	$10^6 \uparrow$	2.5.17
Surface resistivity	MΩ	C-96/35/90	$5 \times 10^6 \sim 5 \times 10^7$	$10^4 \uparrow$	2.5.17
Permittivity 1MHz	-	C-24/23/50	4.5-4.7	5.4 ↓	2.5.5.9
Permittivity 1GHz	-	C-24/23/50	4.0-4.2	-	2.5.5.9
Loss Tangent 1MHz	-	C-24/23/50	0.015-0.020	0.035 ↓	2.5.5.9
Loss Tangent 1GHz	-	C-24/23/50	0.012-0.014	-	2.5.5.9
Arc resistance	SEC	D-48/50+D-0.5/23	120 ↑	60 ↑	2.5.1
Dielectric breakdown	KV	D-48/50	60 ↑	40 ↑	2.5.6
Moisture absorption	%	D-24/23	0.05-0.10	0.35 ↓	2.6.2.1
Flammability	-	C-48/23/50	94V0	94V0	UL94
Peel strength 1 oz	lb/in	288°C x10" solder floating	10-14	6 ↑	2.4.8
Thermal stress	SEC	288°C solder dipping	200 ↑	10 ↑	2.4.13.1
Pressure cooker (2 atm 120°C)	1/2 hr	SEC	288°C dipping	150↑	N/A
	1 hr	SEC	288°C dipping	150↑	N/A
	2 hr	SEC	288°C dipping	150	N/A
Flexural strength	LW	N/mm²	A	480-550	415 ↑
	CW	N/mm²	A	415-480	345 ↑
Dimensional stability X-Y axis	%	E-0.5/170	0.005-0.030	0.050 ↓	2.4.39
Coefficient of thermal expansion					
Z-axis before Tg	ppm/°C	TMA	50-70	N/A	2.4.24
Z-axis after Tg	ppm/°C	TMA	250-350		
Glass transition temp	°C	DSC	135 ± 5	N/A	2.4.25
Decomposition Temperature (Td 5% W/L)	°C	TGA	310	N/A	2.4.24.6

NOTE:

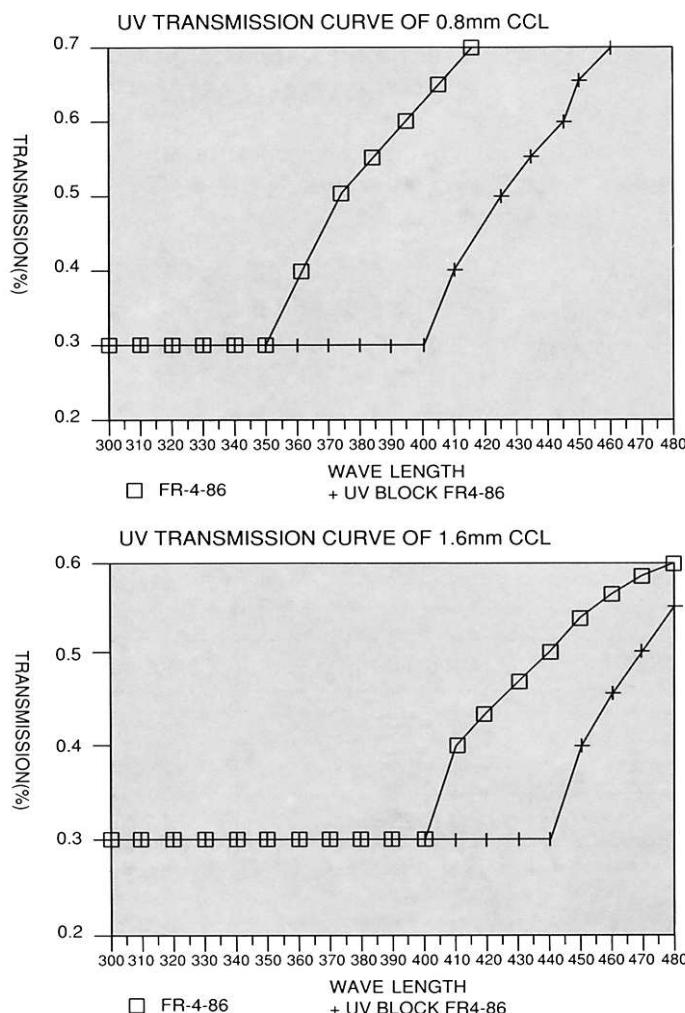
Data shown are nominal values for reference only.

The average value in the table refers to samples of .062" 1/1.

Test method per IPC-TM-650

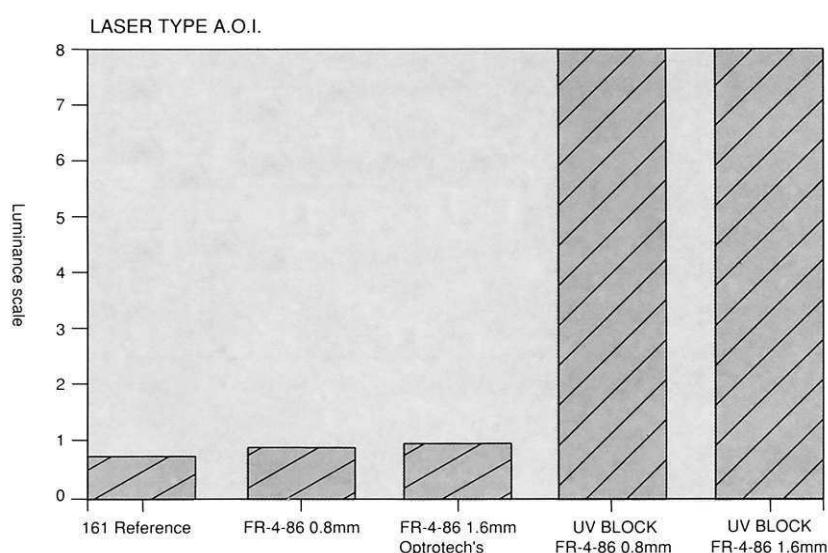


■ Low UV Transmission



■ High luminance of epoxy contrast with copper

FR-4-86 1.6 mm
Orbotech's



■ CERTIFICATION UL

- UL File No. : E98983
- ANSI TYPE:FR-4.0